

6th Generation CoolSiC™

650V SiC Schottky Diode

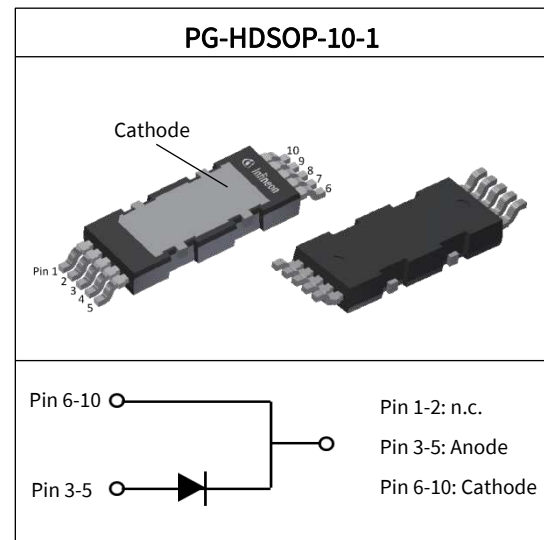
The CoolSiC™ generation 6 (G6) is the leading edge technology from Infineon for the SiC Schottky barrier diodes. The Infineon proprietary innovative G5 technology was enhanced in G6 by introducing further advancements like a novel Schottky metal system. The result is a family of products with improved efficiency over all load conditions, resulting from a lower figure of merit ($Q_C \times V_F$). The CoolSiC™ Schottky diode 650 V G6 has been designed to complement our 600 V and 650 V CoolMOS™ 7 families, meeting the most stringent application requirements in this voltage range.

Table 1 Key performance parameters

Parameter	Value	Unit
V_{RRM}	650	V
Q_C ($V_R = 400$ V)	9.6	nC
E_C ($V_R = 400$ V)	1.6	μJ
I_F ($T_C \leq 150$ °C, $D = 1$)	6	A
V_F ($I_F = 6$ A, $T_j = 25$ °C)	1.25	V

Table 2 Package information

Type / ordering Code	Package	Marking
IDDD06G65C6	PG-HDSOP-10-1	D0665C6



Features

- Best in class forward voltage (1.25 V)
- Best in class figure of merit ($Q_C \times V_F$)
- High dv/dt ruggedness (150 V/ns)

Benefits

- System efficiency improvement
- System cost and size savings due to the reduced cooling requirements
- Enabling higher frequency and increased power density

Potential Applications

- Power factor correction in SMPS
- Solar inverter
- Uninterruptible power supply

Product Validation

- Qualified for industrial applications according to the relevant tests of JEDEC (J-STD20 and JESD22)



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1 Maximum ratings

Table 3 Maximum ratings

Parameter	Symbol	Values			Unit	Note/Test condition
		Min.	Typ.	Max.		
Continuous forward current	I_F	-	-	6	A	$T_C \leq 150\text{ °C}, D = 1$
		-	-	10		$T_C \leq 125\text{ °C}, D = 1$
		-	-	18		$T_C \leq 25\text{ °C}, D = 1$
Surge-repetitive forward current, sine halfwave ¹	$I_{F,RM}$	-	-	26		$T_C = 25\text{ °C}, t_p = 10\text{ ms}$
Surge non-repetitive forward current, sine halfwave	$I_{F,SM}$	-	-	38		$T_C = 25\text{ °C}, t_p = 10\text{ ms}$
		-	-	30		$T_C = 150\text{ °C}, t_p = 10\text{ ms}$
Non-repetitive peak forward current	$I_{F,max}$	-	-	410	$T_C = 25\text{ °C}, t_p = 10\text{ }\mu\text{s}$	
i^2t value	$\int i^2 dt$	-	-	7.2	A ² s	$T_C = 25\text{ °C}, t_p = 10\text{ ms}$
		-	-	4.6		$T_C = 150\text{ °C}, t_p = 10\text{ ms}$
Repetitive peak reverse voltage	V_{RRM}	-	-	650	V	$T_C = 25\text{ °C}$
Diode dv/dt ruggedness	dv/dt	-	-	150	V/ns	$V_R = 0..480\text{ V}$
Power dissipation	P_{tot}	-	-	73	W	$T_C = 25\text{ °C}, R_{thJC,max}$
Operating and storage temperature	T_j	-55	-	175	°C	-
	T_{stg}					

2 Thermal characteristics

Table 4 Thermal characteristics

Parameter	Symbol	Values			Unit	Note/Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction-case	R_{thJC}	-	1.2	2.0	K/W	-
Thermal resistance, junction-ambient	R_{thJA}	-	-	62		Device on PCB, minimal footprint
Thermal resistance, junction-ambient for SMD version	R_{thJA}	-	35	45		Device on 40*40*1.5 mm epoxy PCB FR4 (one layer, 70 μm thickness) with 6 cm^2 copper for cathode connection and cooling, PCB vertically placed without air stream cooling
Soldering temperature	T_{sold}	-	-	260	°C	Allowed only reflow soldering

¹ The surge-repetitive forward current test was performed with 1000 pulses (half-wave rectified sine with the 10 ms period).

3 Electrical characteristics

3.1 Static characteristics

Table 5 Static characteristics

Parameter	Symbol	Values			Unit	Note/Test condition
		Min.	Typ.	Max.		
DC blocking voltage	V_{DC}	650	–	–	V	$T_j = 25\text{ °C}$
Diode forward voltage	V_F	–	1.25	1.35		$I_F = 6\text{ A}, T_j = 25\text{ °C}$
		–	1.5	–		$I_F = 6\text{ A}, T_j = 150\text{ °C}$
Reverse current	I_R	–	0.6	20	μA	$V_R = 420\text{ V}, T_j = 25\text{ °C}$
		–	20	–		$V_R = 420\text{ V}, T_j = 125\text{ °C}$
		–	46	–		$V_R = 420\text{ V}, T_j = 150\text{ °C}$

3.2 AC characteristics

Table 6 AC characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Total capacitive charge	Q_C	–	9.6	–	nC	$V_R = 400\text{ V}, T_j = 150\text{ °C},$ $di/dt = 200\text{ A}/\mu\text{s}, I_F \leq I_{F,MAX}$
Total capacitance	C	–	302	–	pF	$V_R = 1\text{ V}, f = 1\text{ MHz},$ $T_j = 25\text{ °C}$
		–	18	–		$V_R = 300\text{ V}, f = 1\text{ MHz},$ $T_j = 25\text{ °C}$
		–	17	–		$V_R = 600\text{ V}, f = 1\text{ MHz},$ $T_j = 25\text{ °C}$

4 Diagrams

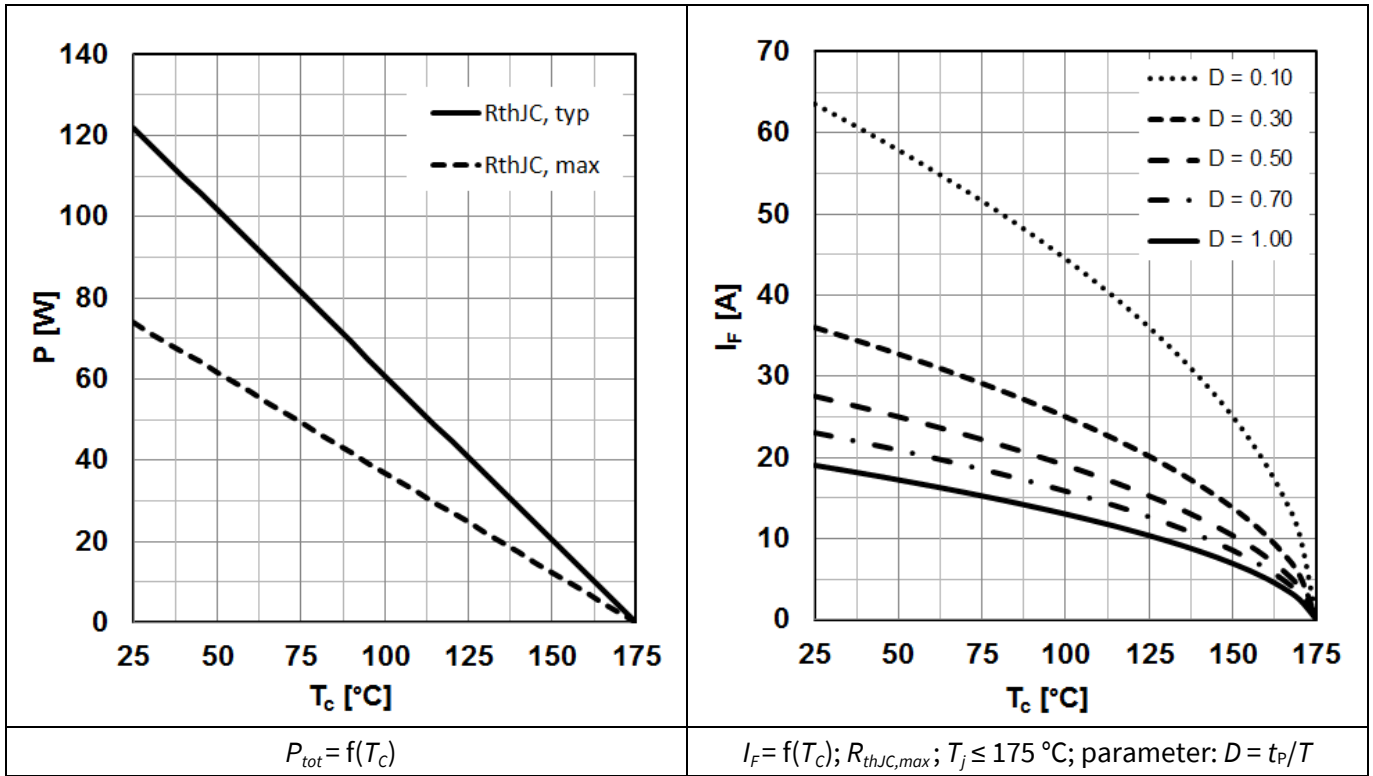


Figure 1 Power dissipation

Figure 2 Max. forward current

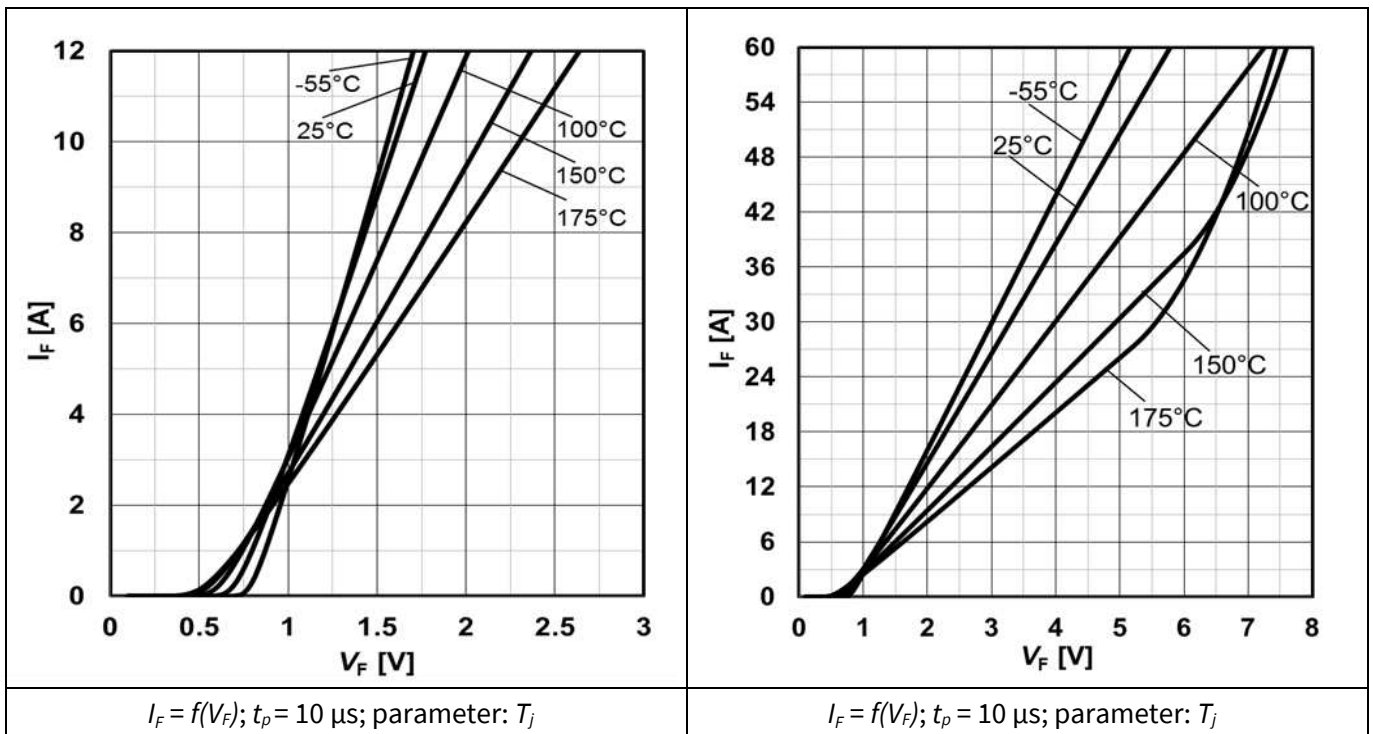
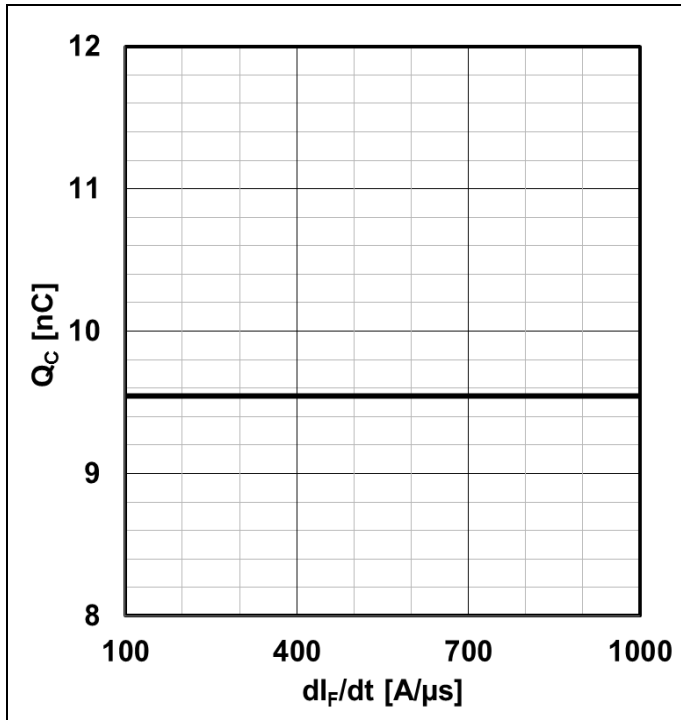


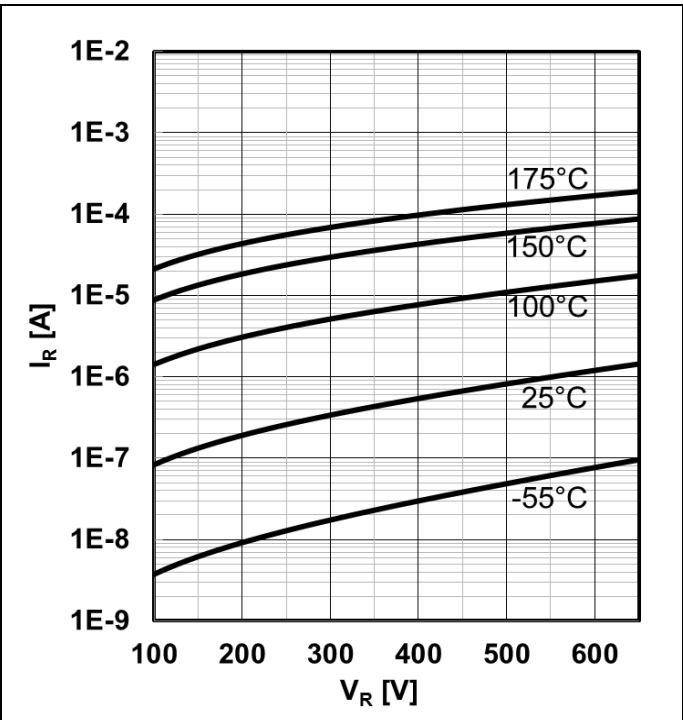
Figure 3 Typ. forward characteristics

Figure 4 Typ. forward characteristics in surge current



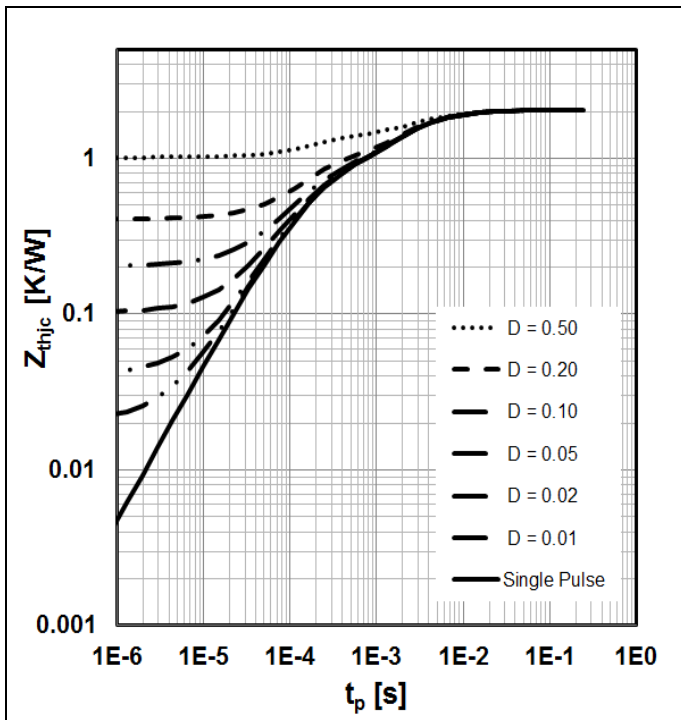
$Q_c = f(di_F/dt); T_j = 150\text{ °C}; V_R = 400\text{ V}; I_F \leq I_{F,max}$

Figure 5 Typ. cap. charge vs. current slope



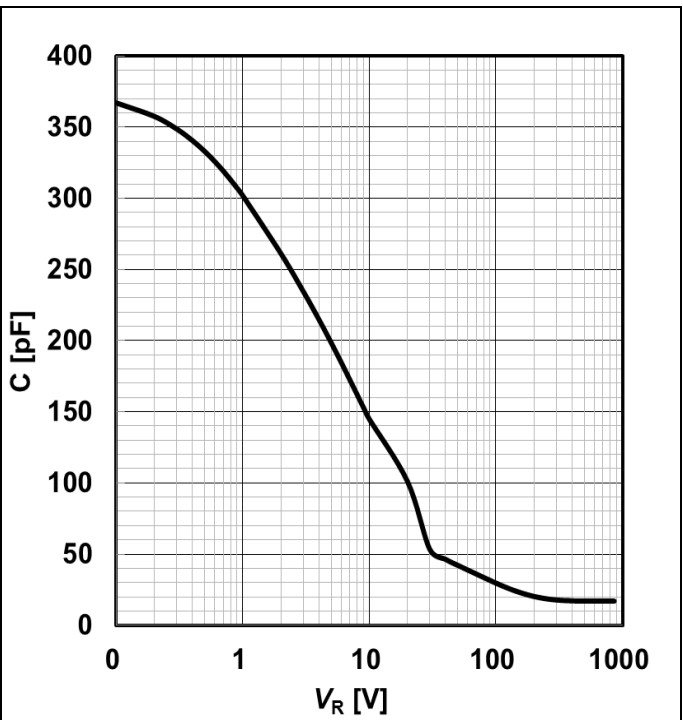
$I_R = f(V_R); \text{parameter: } T_j$

Figure 6 Typ. reverse current vs. reverse voltage



$Z_{th,jc} = f(t_p); \text{parameter: } D = t_p/T$

Figure 7 Max. transient thermal impedance



$C = f(V_R); T_j = 25\text{ °C}; f = 1\text{ MHz}$

Figure 8 Typ. capacitance vs. reverse voltage

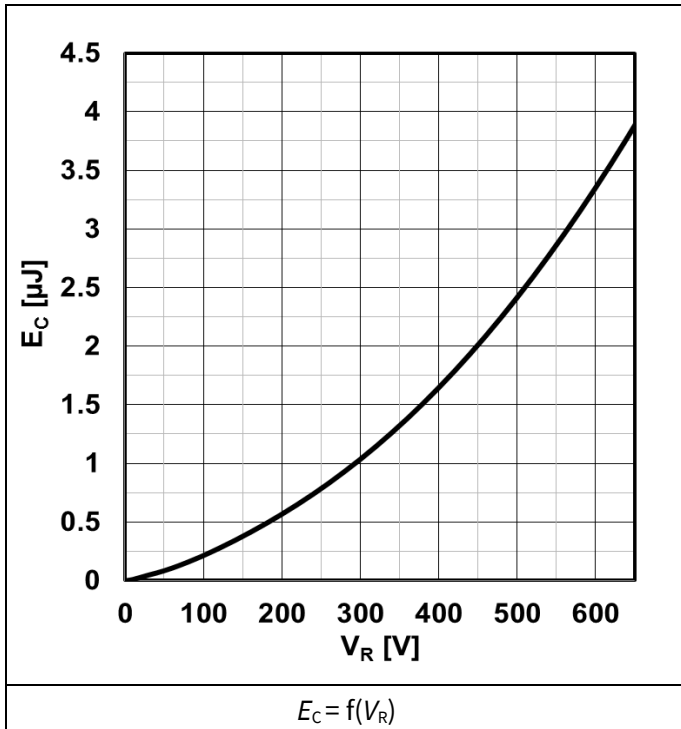


Figure 9 Typ. capacitance stored energy

5 Simplified forward characteristic

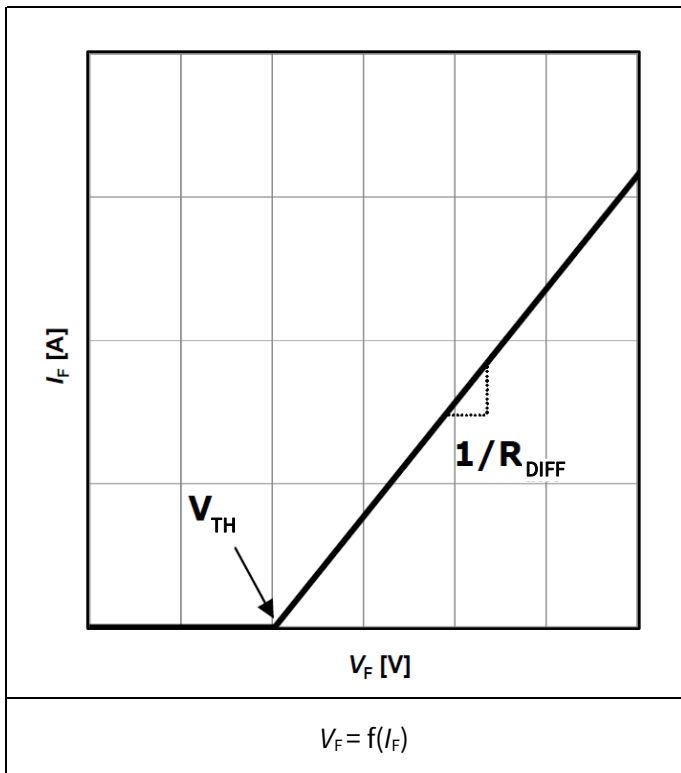


Figure 10 Equivalent forward current curve

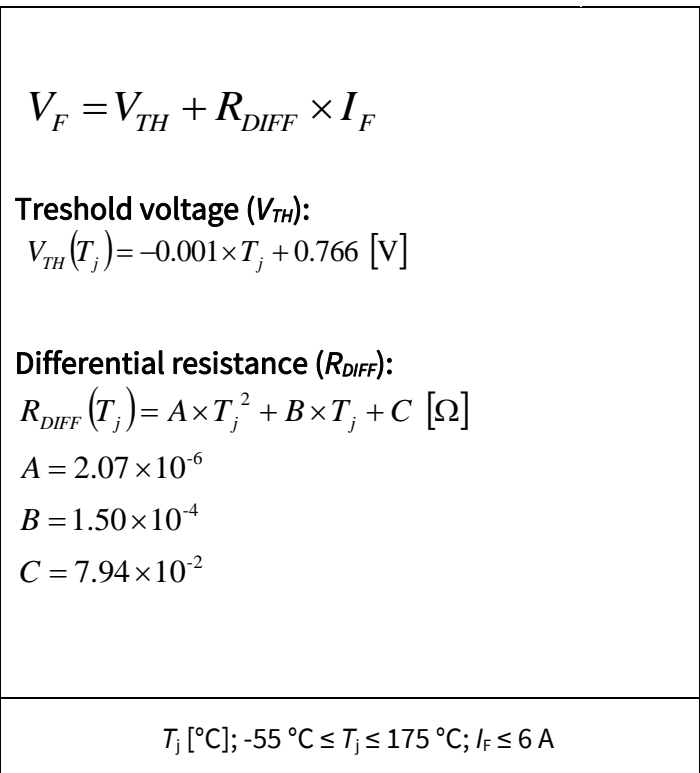


Figure 11 Mathematical Equation

6 Package outlines

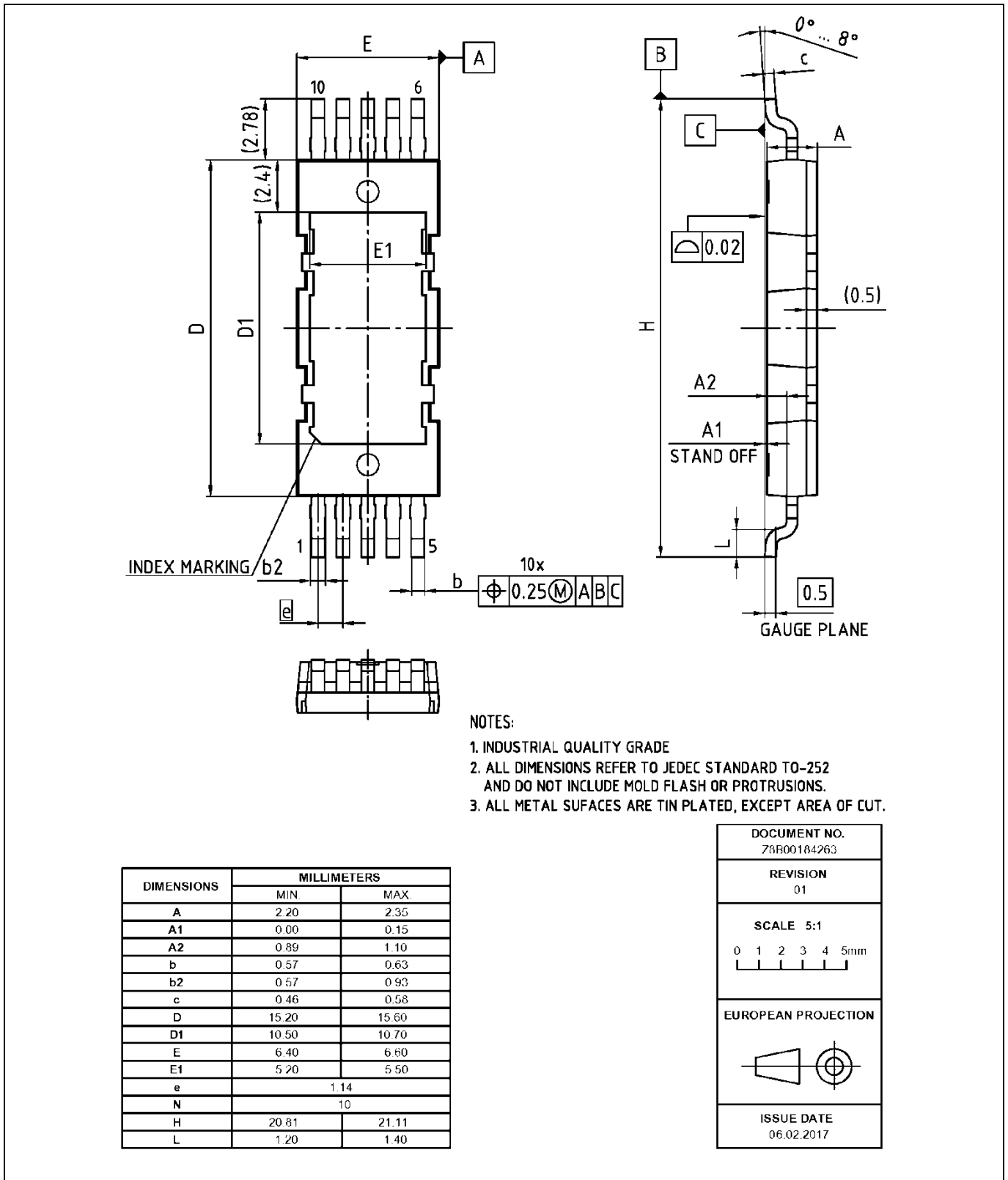


Figure 12 Outlines of the package PG-HDSOP-10-1, dimensions in millimeters

Revision History

IDDD06G65C6

Revision: 2018-02-26, Rev. 2.0

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2018-02-26	Release of final version

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